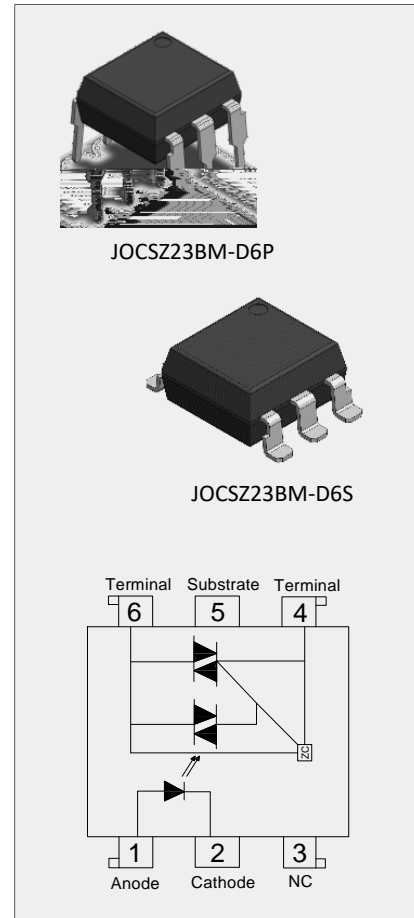




The products are 6-pin solid-state relay opto-couplers. The device combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon zero-crossing photo triac to drive a power triac in a plastic DIP6 package with different lead forming options. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors to 265 V_{AC} peripherals.



High isolation 5000 Vrms

DC input with triac output

Operating temperature range - 40°C to 110 °C

REACH & RoHS compliance

HBM: H3B; MM: M4; CDM: C3

CQC approved

VDE approved

UL approved

(Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I _F	50	mA
	Peak Forward Current	I _{FP}	1	A
	Reverse Voltage	V _R	6	V
	Power Dissipation	P _D	75	mW
Output	Repetitive peak off-state voltage	V _{DRM}	600	V
	Repetitive peak off-state voltage	V _{RRM}	600	V
	Critical rate of rise of on-state current	di/dt	100	A/μs
	On-state RMS Current (T _a 80 °C)	I _{T(RMS)}	0.3	A
	Non repetitive surge peak on-state current (full cycle , t _p =20ms)	I _{TSM}	3	A
	junction to case (AC)	R _{th(j-c)}	65	/W

Isolation Voltage	V_{iso}	5000	Vrms
Operating Temperature	T_{opr}	-40~110	
Junction Temperature	T_j	125	
Storage Temperature	T_{stg}	-40~125	
Soldering Temperature	T_{sol}	260	
Peak pulse voltage ($T_j=25$; non-repetitive,off-state)	V_{pp}	3	kV

100 μ s pulse, 100Hz frequency
AC for 1minute, R.H.=40~60%

(Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10mA$	-	1.2	1.5	V
	Reverse Current	I_R	$V_R=6V$	-	-	1	μA

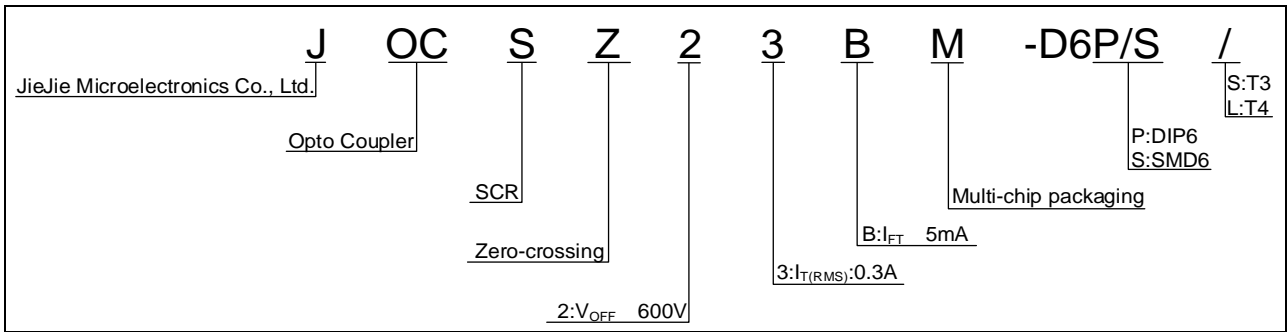


FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

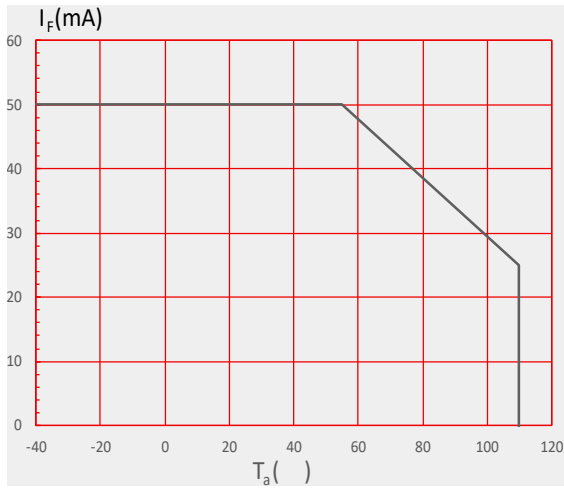


FIG.3: Forward Current vs. Forward Voltage

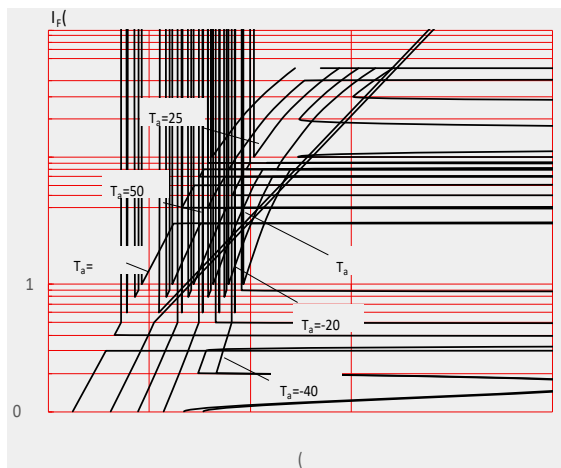


FIG.5: Off-state Terminal Current vs Off-state Terminal Voltage

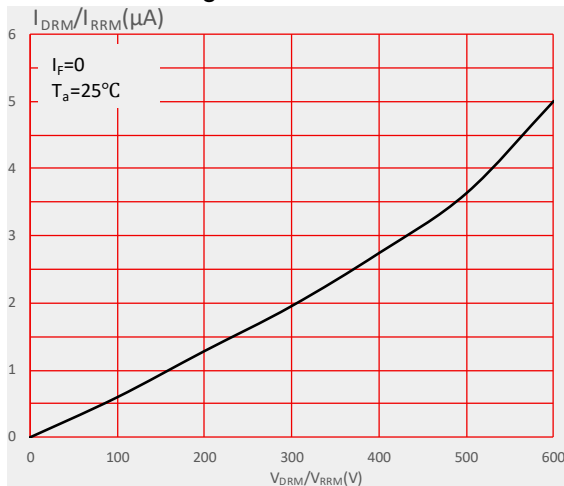


FIG.2: On-state Terminal Current vs. Ambient Temperature

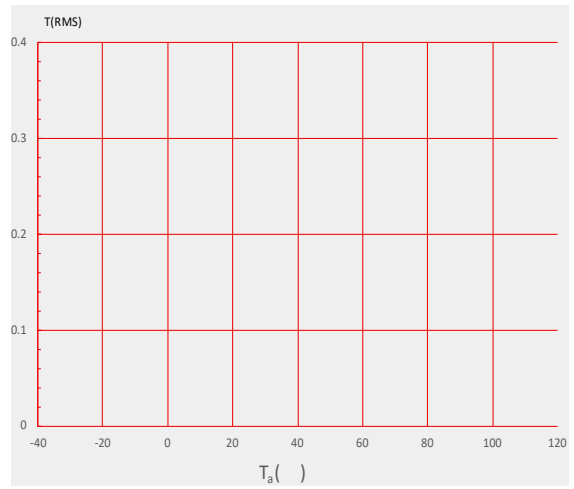


FIG.4: Forward Voltage vs. Ambient Temperature

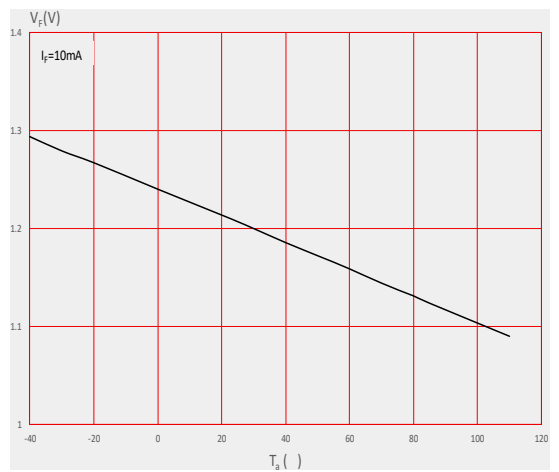


FIG.6: Normalized Trigger Current vs. Ambient Temperature

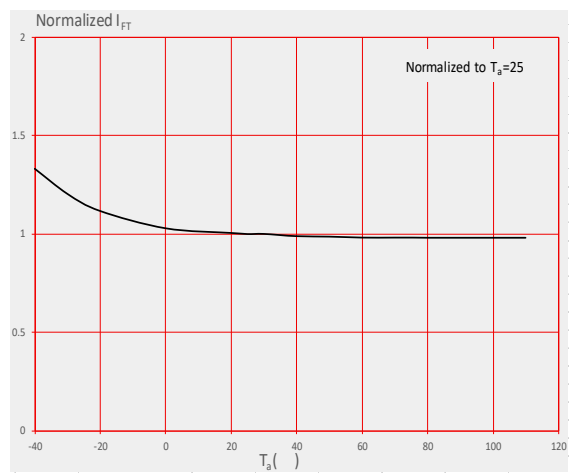


FIG.7: On-state characteristics

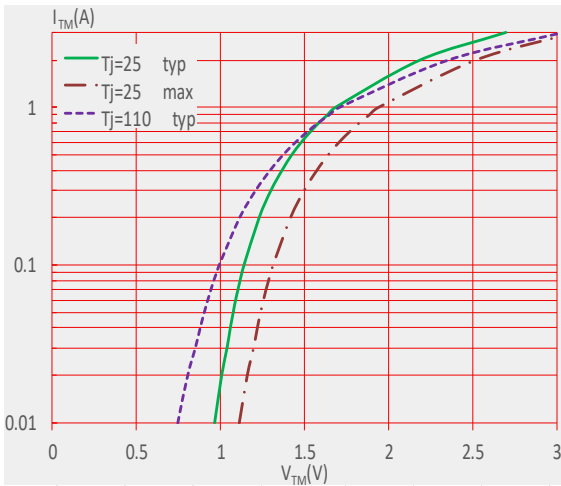


FIG.8: Normalized Holding Current vs. Ambient Temperature

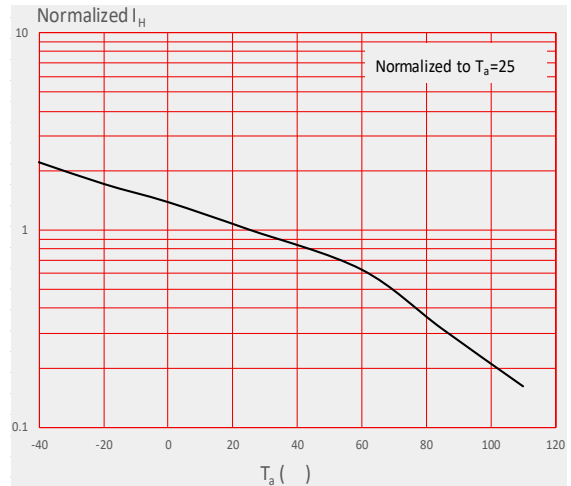


FIG.9: Turn On Time vs. Forward Current

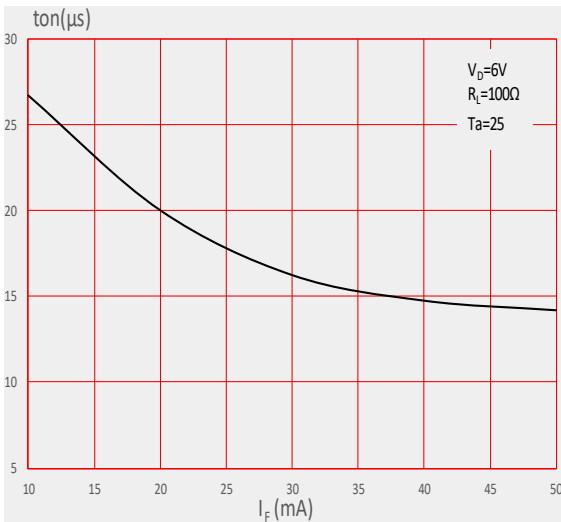


FIG.10: Normalized Inhibit Voltage vs. Ambient Temperature

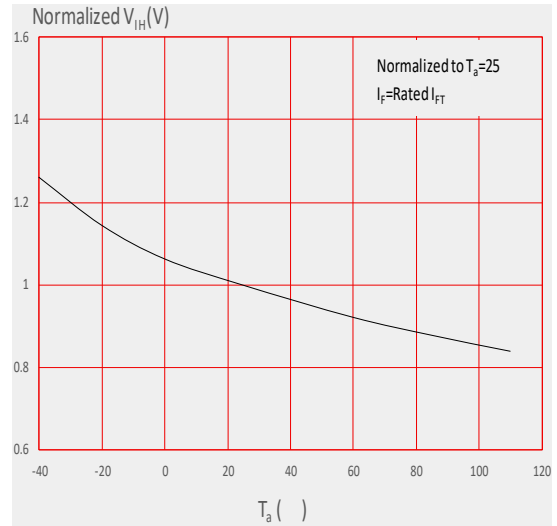


FIG.11: Test Circuits of Turn On Time

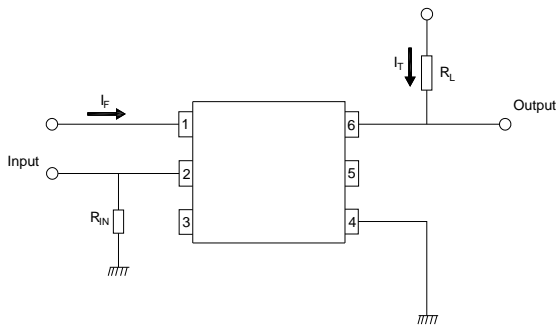


FIG.12: Waveforms of Turn On Time

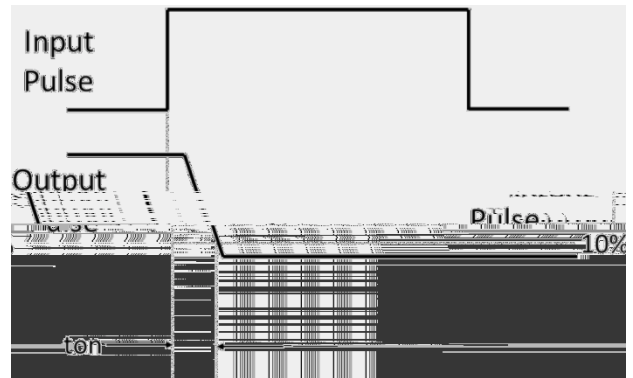
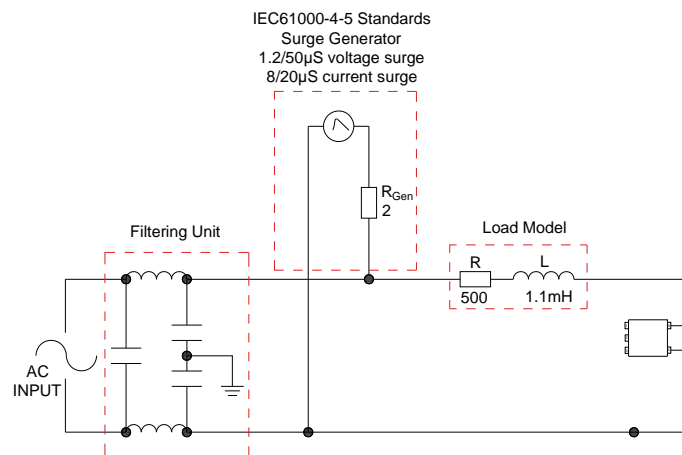
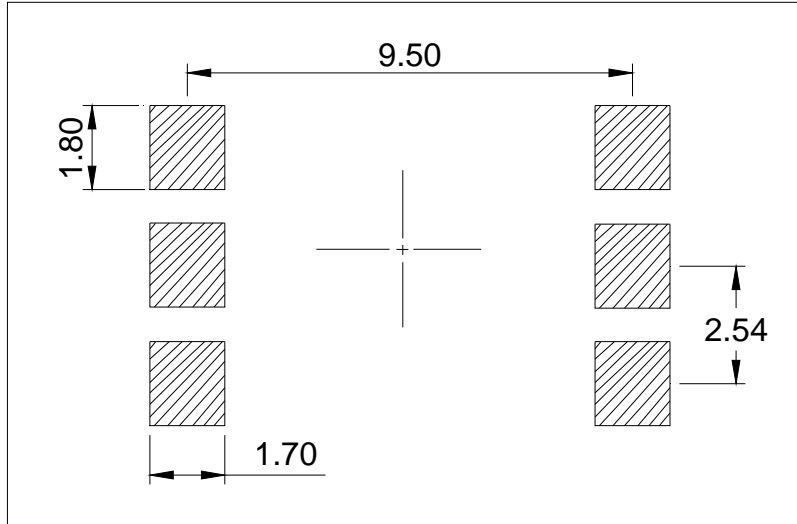


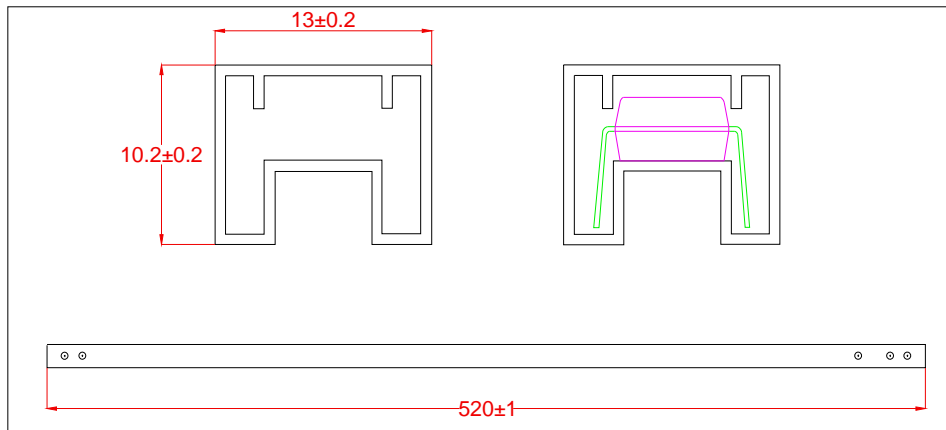
FIG.13: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



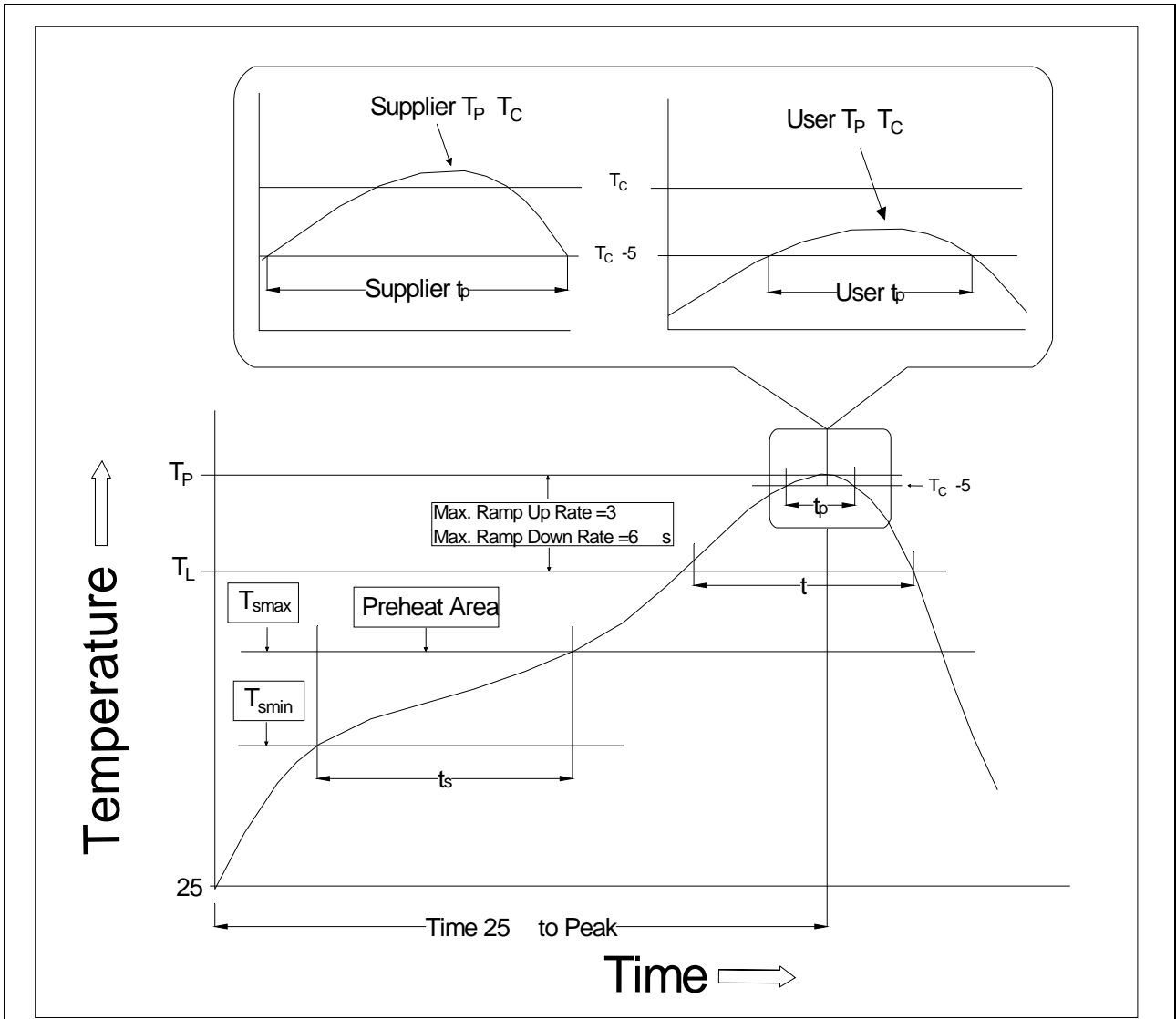
Option SMD



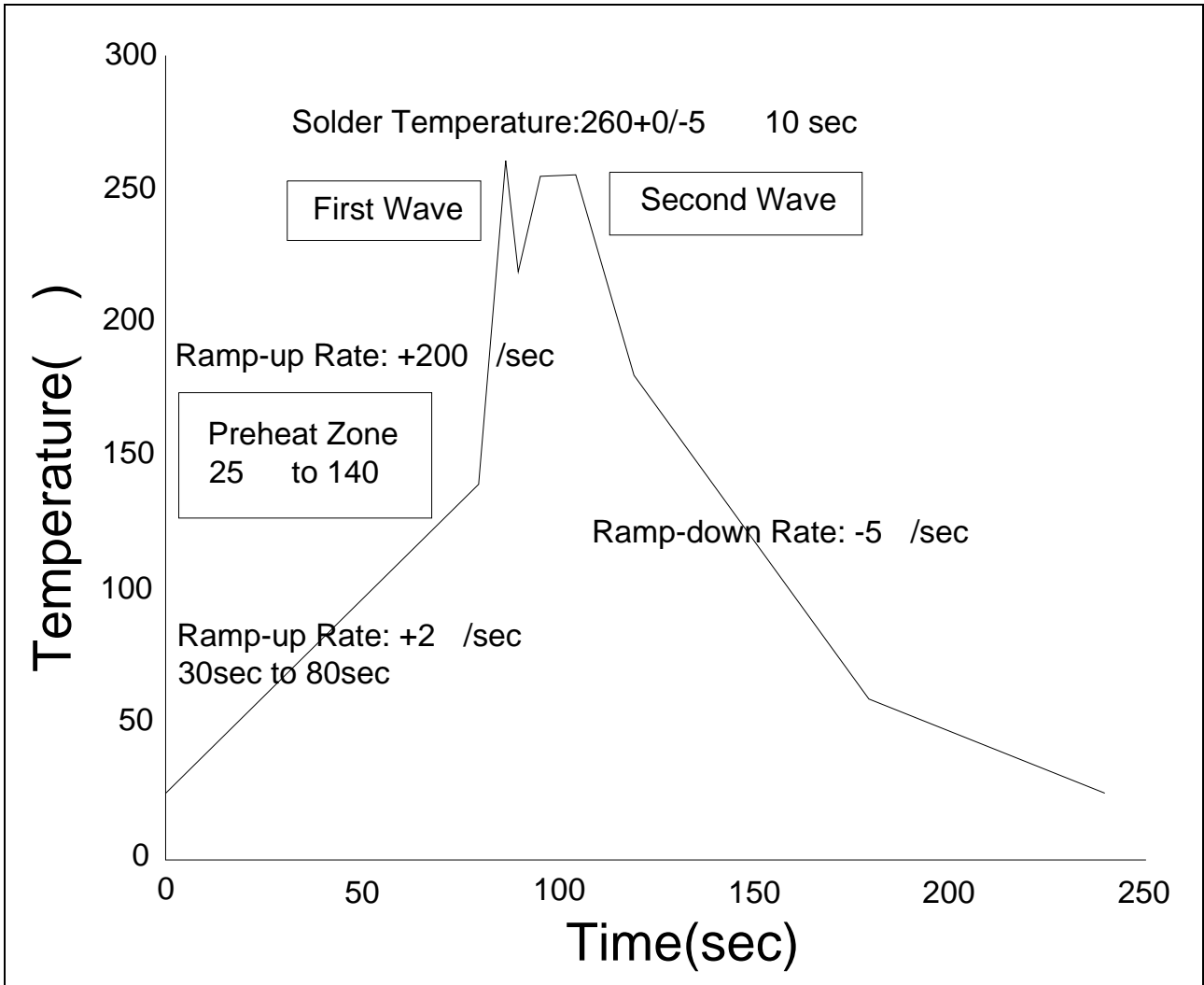
Standard DIP



JOC SZ23BM



Temperature Min. (T_{smin})	150
Temperature Max. (T_{smax})	200
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds
Ramp-up Rate (t_L to t_P)	3 /second max.
Liquidus Temperature (T_L)	217
Time (t_L) Maintained Above (T_L)	60-120 seconds
Peak Body Package Temperature	260 +0 /-5
Time (t_P) within 5 of 260	10 seconds
Ramp-down Rate (T_P to T_L)	6 /second max.




Soldering Temperature	360 ± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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